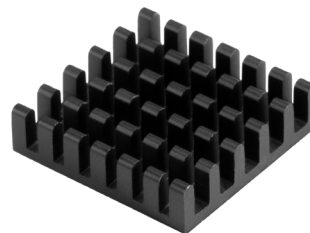




**MODEL:** HSB10-232306 | **DESCRIPTION:** HEAT SINK

**FEATURES**

- BGA design
- top mount
- aluminum alloy
- black anodized finish



**MODEL**

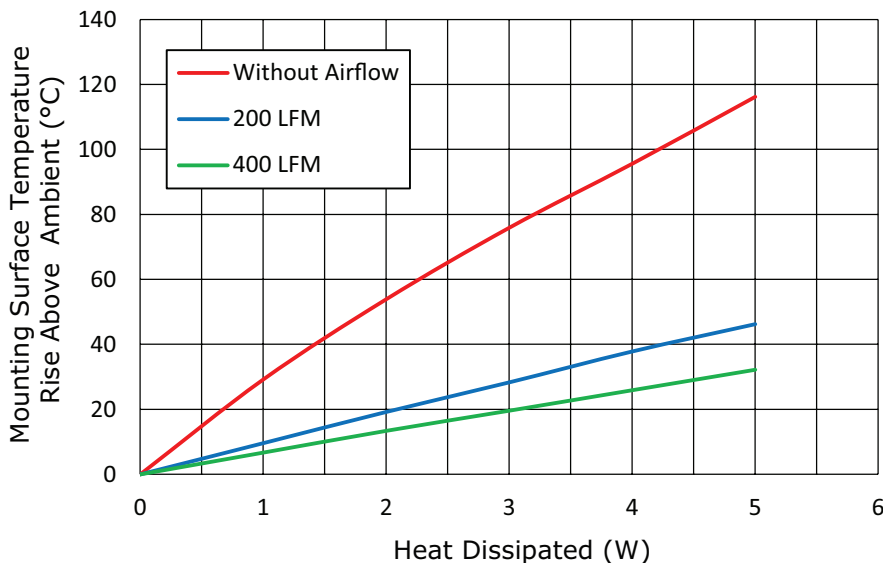
HSB10-232306	thermal resistance <sup>1</sup>			power dissipation <sup>1</sup> @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	
	25.46	29.2	9.6	6.7

Note: 1. See performance curves for full thermal resistance details.

**PERFORMANCE CURVES**

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T <sub>hs</sub> - T <sub>a</sub> ) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	29.2	9.6	6.7
2	53.9	19.2	13.4
3	75.9	28.3	19.6
4	95.6	37.8	25.9
5	116.2	46.2	32.2

T<sub>hs</sub>: "hot spot" temperature measured on the heatsink  
T<sub>a</sub>: ambient temperature



**CUI DEVICES** | **MODEL:** HSB10-232306 | **DESCRIPTION:** HEAT SINK

## MECHANICAL DRAWING

units: mm  
tolerance: ±0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	4.8 g

